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PATENT NUMBER and ISSUE DATE

12/11/2001 1283 689 1142 17CO PPLICANTS: Ushiki Takehito; Tsunoda Hitoshi; CONTINUING DATA VERIFIED: IIS APPLICATION IS A DIV OF 09/346,004 07/01/1999 G L POREIGN APPLICATIONS VERIFIED: DAPAN 10-208633 07/08/1998 G L POPUB DO NOT PUBLISH RESCIND ATTORNEY DOCKET NO	PL NUM FILING	DATE	CLASS	SUBCLASS	GAU 1772		EXAMINER	
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